

Title (en)

METHOD OF PRODUCING A FEEDTHROUGH ON A CIRCUIT BOARD

Title (de)

VERFAHREN ZUR HERSTELLUNG EINER DURCHKONTAKTIERUNG AUF EINER LEITERPLATTE

Title (fr)

PROCEDE DE REALISATION D'UNE TRAVERSEE DANS UNE PLAQUETTE A CIRCUIT IMPRIME

Publication

**EP 0738456 A1 19961023 (DE)**

Application

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Abstract (en)

[origin: US5799393A] PCT No. PCT/DE95/01497 Sec. 371 Date Sep. 23, 1996 Sec. 102(e) Date Sep. 23, 1996 PCT Filed Oct. 27, 1995 PCT Pub. No. WO96/15651 PCT Pub. Date May 23, 1996A method for producing a plated-through hole on a printed-circuit board, whereby the printed-circuit board is initially bored, catalyzed, and patterned. The plated-through hole is then fashioned in an electrochemical deposition process so as to make it functional for the through-hole mounting of electrical components. The plating process is preferably carried out with nickel or nickel compounds, so that no additional corrosion protection is required. A direct bonding to the contact lands can be achieved by coating the contact lands with gold or palladium.

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